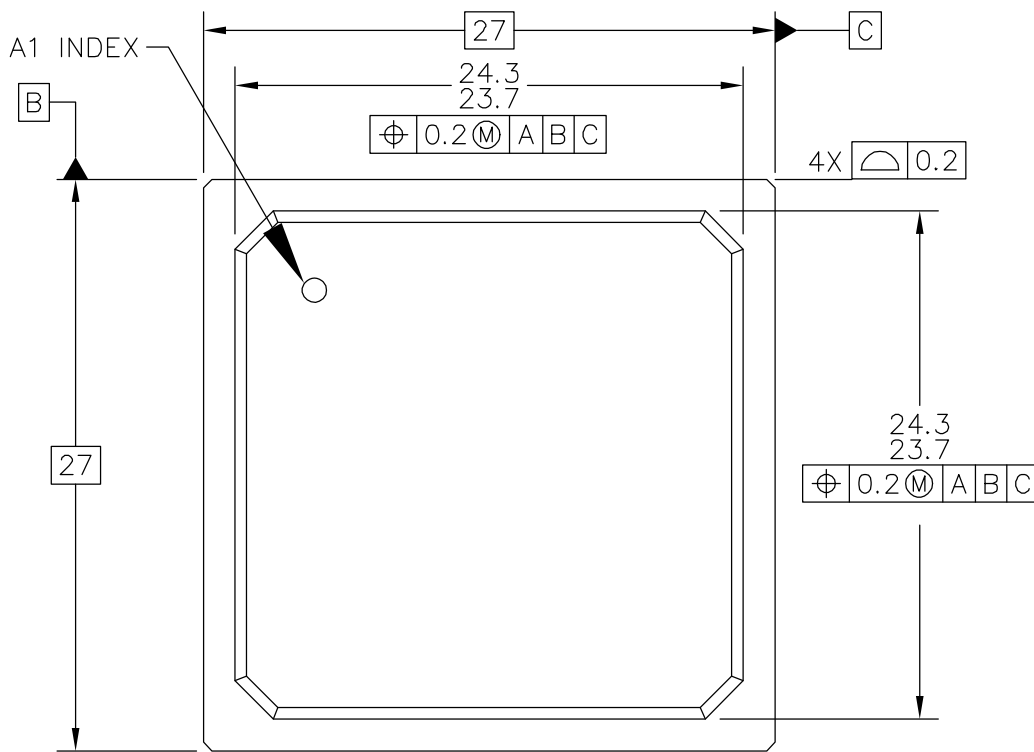
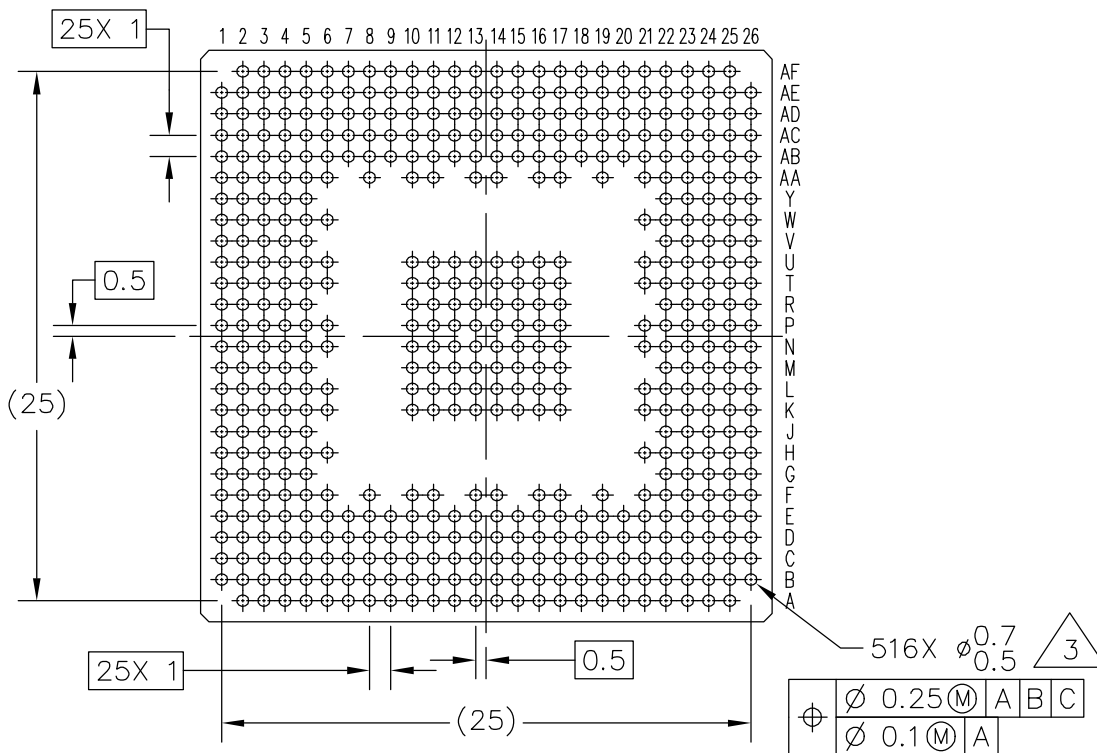
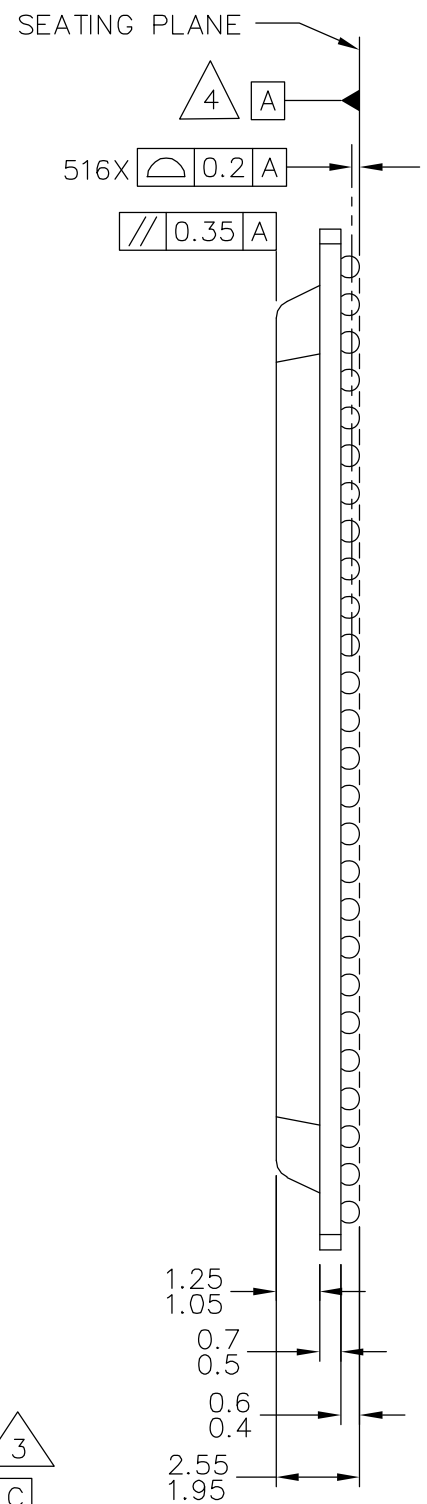




TOP VIEW



BOTTOM VIEW



SIDE VIEW

© FREESCALE SEMICONDUCTOR, INC.  
ALL RIGHTS RESERVED.

# MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: 516 I/O, PBGA  
27 X 27 PKG,  
1 MM PITCH (OMPAC)

DOCUMENT NO: 98ARS10503D

REV: C

CASE NUMBER: 1164A-01

19 JAN 2010

STANDARD: JEDEC MS-034 AAL-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DELETED

|                                                         |                                                     |                              |  |                            |  |
|---------------------------------------------------------|-----------------------------------------------------|------------------------------|--|----------------------------|--|
| © FREESCALE SEMICONDUCTOR, INC.<br>ALL RIGHTS RESERVED. |                                                     | MECHANICAL OUTLINE           |  | PRINT VERSION NOT TO SCALE |  |
| TITLE:                                                  | 516 I/O, PBGA<br>27 X 27 PKG,<br>1 MM PITCH (OMPAC) | DOCUMENT NO: 98ARS10503D     |  | REV: C                     |  |
|                                                         |                                                     | CASE NUMBER: 1164A-01        |  | 19 JAN 2010                |  |
|                                                         |                                                     | STANDARD: JEDEC MS-034 AAL-1 |  |                            |  |